



### Discription

The HDF2S6M5CT,L3F protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD. It gives designer the flexibility to protect one unidirectional line in applications where arrays are not practical.



DFN1006-2L

### Features

- ★ Transient protection for high-speed data lines  
IEC 61000-4-2(ESD) ±20kV (Contact)  
±20kV (Air)  
IEC 61000-4-4(EFT) 40A (5/50 ns)
- ★ Peak power dissipation: 60W (8/20us)
- ★ Working voltages : 5V
- ★ Ultra-small package (1.0mmx0.6mmx0.5mm)
- ★ Protects one data, control line
- ★ Low capacitance: 0.4pF (Typical)
- ★ Low clamping voltage
- ★ Low leakage current



Circuit Diagram

### Ordering information

Product ID	Pack	Qty(PCS)
HDF2S6M5CT,L3F	DFN1006-2L	10000

### Absolute Ratings(Tamb = 25°C)

Symbol	Parameter	Value	Units
P <sub>PP</sub>	Peak Pulse Power (t <sub>p</sub> = 8/20 μ s)	60	W
T <sub>L</sub>	Maximum lead temperature for soldering during 10s	260	°C
T <sub>stg</sub>	Storage Temperature Range	-55 to +150	°C
T <sub>op</sub>	Operating Temperature Range	-55 to +150	°C
T <sub>j</sub>	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD) air discharge contact discharge	±20 ±20	KV
	IEC61000-4-4 (EFT)	40	A

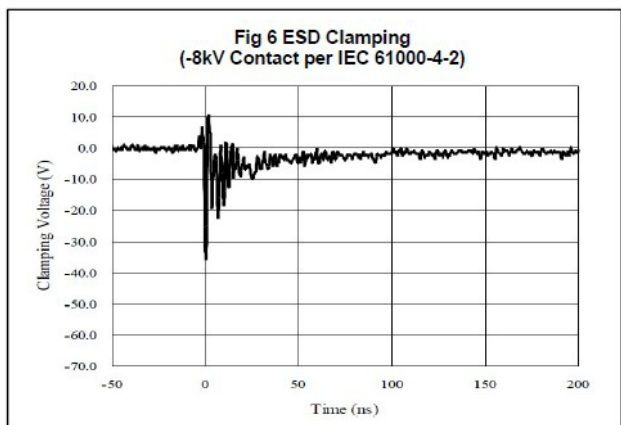
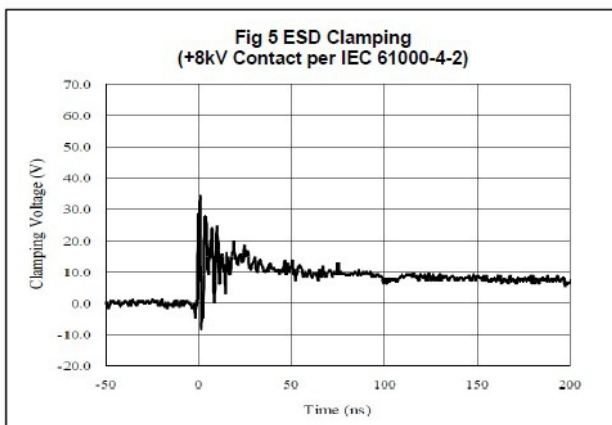
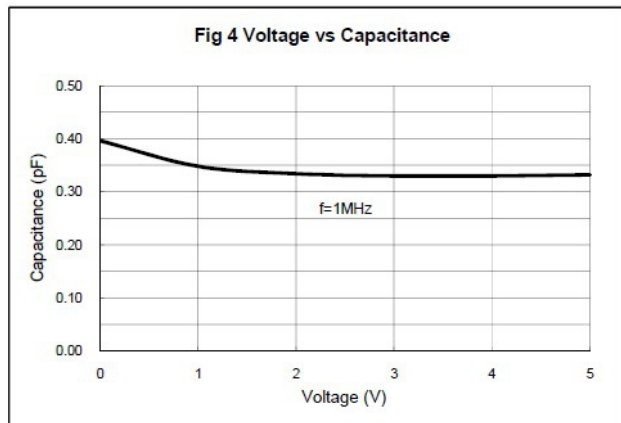
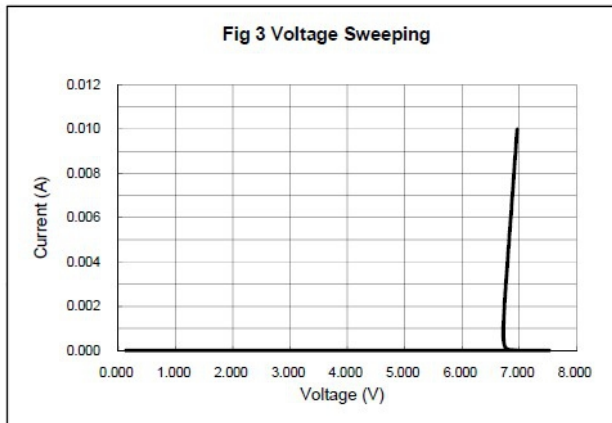
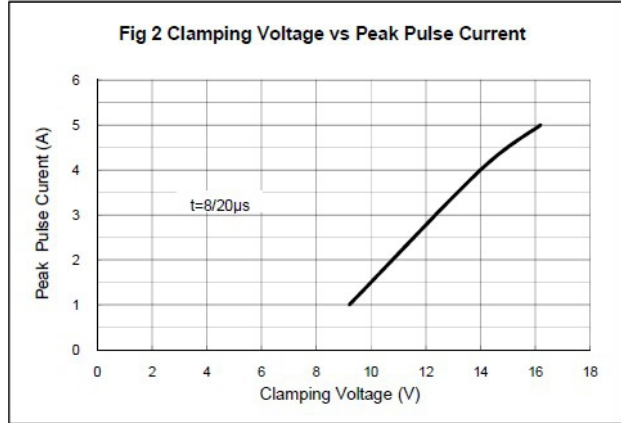
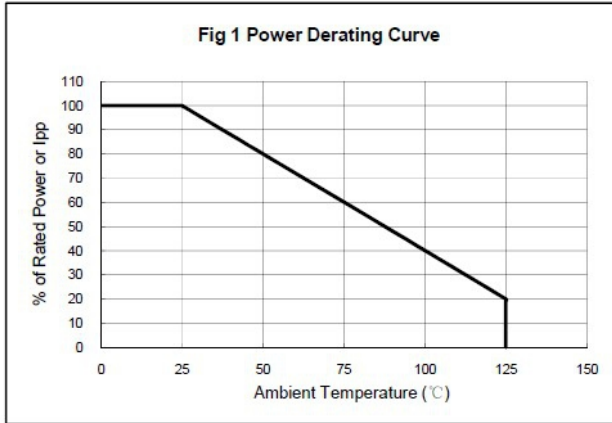


**Electrical Characteristics** Ratings at 25°C

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
$V_{RWM}$	Reverse Working Voltage				5.0	V
$V_{BR}$	Reverse Breakdown Voltage	$I_T = 1mA$	6.0			V
$I_R$	Reverse Leakage Current	$V_{RWM} = 5V$			100	nA
$V_C$	Clamping Voltage	$I_{RWM} = 1A, t_p = 8/20\mu s$			10	V
		$I_{RWM} = 4A, t_p = 8/20\mu s$			15	V
$C_J$	Junction Capacitance	$V_R = 0V, f = 1MHz$		0.60	0.80	pF



## Typical Characteristics





### Outline And Dimensions



TOP VIEW

BOTTOM VIEW

DFN1006-2L			
Dim	Min	Typ	Max
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	-	0.64	-
L	0.44	0.49	0.54
b	0.20	0.25	0.30
A	0.43	0.48	0.53
A1	0	-	0.05
A3	0.127REF.		
All Dimensions in mm			



SIDE VIEW

### Soldering Footprint



Dimensions	(mm)
c	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70



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